

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
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RECEIVING PARTY DATA																			
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;">Name:</td><td>Hynix Semiconductor, Inc.</td></tr> <tr><td>Street Address:</td><td>San 136-1, Ami-ri, Bubal-eub, Ichon-si</td></tr> <tr><td>Internal Address:</td><td>Gyeonggi-do</td></tr> <tr><td>City:</td><td>Ichon</td></tr> <tr><td>State/Country:</td><td>KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF</td></tr> <tr><td>Postal Code:</td><td>467-860</td></tr> </table>		Name:	Hynix Semiconductor, Inc.	Street Address:	San 136-1, Ami-ri, Bubal-eub, Ichon-si	Internal Address:	Gyeonggi-do	City:	Ichon	State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF	Postal Code:	467-860						
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CORRESPONDENCE DATA																			
<p>Fax Number: (214)978-3099</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Email: nicole.m.otis@bakernet.com</p> <p>Correspondent Name: Baker & McKenzie LLP</p> <p>Address Line 1: 2001 Ross Ave.</p> <p>Address Line 2: Suite 2300</p> <p>Address Line 4: Dallas, TEXAS 75201</p>																			

CH \$40.00 12170254

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PATENT
REEL: 021390 FRAME: 0237

ATTORNEY DOCKET NUMBER:

95210324-200218

NAME OF SUBMITTER:

Noel C. Gillespie

Total Attachments: 5

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ASSIGNMENT

WHEREAS, I the undersigned inventor of residence as listed, have invented certain new and useful improvements as below entitled, for which an application for United States Letters Patent is made, said application having been designated as set forth below and filed on or about the date set forth below; and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"),

with an address of: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

desires to acquire the entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent(s) that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, continuations, continuations-in-part and extensions thereof; and I authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title and interest in and to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world, including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

I will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, I will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

Invention Name: **A LOW POWER, HIGH SPEED RECEIVER CIRCUIT FOR
USE IN A SEMICONDUCTOR INTEGRATED CIRCUIT**

Serial No.: 12/170,254

Date Filed: July 9, 2008

I hereby grant JOHN G. FLAIM, Registration No. 37,323, BRIAN C. McCORMACK, Registration No. 36,601, WILLIAM D. McSPADDEN, Registration No. 44,234, JAMES H. ORTEGA, Registration No. 50,554, RICHARD V. WELLS, Registration No. 53,757, HOWARD WISNIA, Registration No. 37,502, NOEL C. GILLESPIE, Registration No. 47,596, ROGER C. KUAN, Registration No. 56,558, KEVIN O'BRIEN, Registration No. 30,578, JAMES P. CONLEY, Registration No. 52,459, and all practitioners with the firm of Baker & McKenzie LLP (Customer Number 23562) with an office at 2001 Ross Avenue, Suite 2300, Dallas, TX 75201, the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned further declares that all statements made herein of his/her own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful and false statements may jeopardize the validity of the application or any patent issued thereon.

Signature of Inventor: TOSU Oh

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Citizenship: Korean

Date: 2008.6.24

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Date: 2008. 6. 24

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Signature of Inventor: Choi Haerang
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Signature of Inventor: Ji Wang Lee

Inventor(s) Name: Ji Wang, LEE

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Citizenship: Korean

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